

AMENDMENTS TO THE CLAIMS

The below listing of claims replaces all prior versions, and all prior listings, of claims in the application.

Listing of Claims:

1-11. (cancelled).

12. (original) A method of manufacturing a contactor used for testing an integrated circuit electronic component provided with a plurality of electrodes, said method comprising the steps of:

a) preparing a wiring substrate having an insulating base material and a first conductive layer; and

b) forming contacts by mechanically pressing said wiring substrate such that said first conductive layer is plastically deformed at positions corresponding to said electrodes.

13. (original) The method as claimed in claim 12, wherein said step a) comprises the step of forming holes in said insulating base material at positions corresponding to said electrodes,

and wherein said method further comprises the step of:

c) providing reinforcement members on said contacts a first surface of said contacts, said first surface being facing towards said holes.

14-20. (cancelled).

21. (new) The method as claimed in claim 12, wherein said first conductive layer is a continuous structure at a point of contact with the electrodes.